

2022 Master Class Series

# NEW WAYS TO WIRE AND INTEGRATE CHIPS

May 26, 2022 at 9:00 AM PT/12:00 PM ET

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## REGINA FREED

**Vice President**  
Alx™ Solutions

Regina Freed has more than 20 years of experience in the semiconductor industry, managing semiconductor process and equipment development for both logic and memory processes, including co-optimization between deposition and etch, lithography, metrology, and defect inspection. At Applied Materials, Regina leads our Alx™ program that enables us and our customers to accelerate development and ramp through Actionable Insights as well as control our processes to deliver improved process windows, enabling customers to scale faster and at lower cost, while optimizing device performance.

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**Kevin Moraes, Ph.D.**  
**Vice President**  
Products and Marketing

Kevin Moraes is Vice President of Products and Marketing in the Semiconductor Products Group at Applied Materials, Inc. He leads teams that develop product strategies and investment priorities, manage product lines, and communicate strategies to stakeholders. Previously he was vice president of Global Product Management for Metal Deposition Products, where he was responsible for strengthening Applied's leadership position and extending the product roadmaps for ALD, CVD, PVD, and metal deposition applications. Dr. Moraes received his Ph.D. in materials science and engineering from Rensselaer Polytechnic Institute, and a bachelor's degree in chemical engineering from Annamalai University. He also holds an MBA from the Hass School of Business at the University of California, Berkeley.

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## Mehul Naik, Ph.D.

**Managing Director**

Advanced Product Technology Development

Mehul Naik is Managing Director and Principal Member of Technical staff with the Advanced Product Technology Development team in the Semiconductor Products Group at Applied Materials. He is responsible for the Logic Program working on inflection mapping and leading cross-functional programs in the Transistor and Interconnect area. He has authored over 60 publications and holds over 70 U.S. patents. Mehul holds a Ph.D. in Chemical Engineering from Rensselaer Polytechnic University.

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**Sundar Ramamurthy, Ph.D.**  
**Group Vice President**  
Epitaxy, Packaging, and ICAPS Business Units

Dr. Sundar Ramamurthy is responsible for Applied's business in wafer-level packaging, specialty semiconductors, and epitaxy markets. Sundar leads an integrated cross-company team to fuel growth in some of the fastest growing markets in the semiconductor industry. Over the past two decades, Sundar and his team have delivered profitable growth for Applied in multiple technologies – rapid thermal processing, plasma doping, physical vapor deposition, and atomic layer and chemical vapor deposition of thin metal films. He led teams that commercialized 20+ new products to solve critical transistor and interconnect scaling challenges by introducing new materials and interface engineering solutions into volume manufacturing. Sundar holds a Ph.D. in materials science and engineering from the University of Minnesota. He has more than 30 patents granted or pending. He is also an active mentor with the Miller Center in Santa Clara University for accelerating social enterprises.

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**RAMAN ACHUTHARAMAN**  
**Group Vice President**  
Head of Technology, Strategy and Marketing

Dr. Raman Achutharaman leads the Semiconductor Products Group in defining the technology roadmap; developing the strategic plan to strengthen Applied's leadership in core wafer fabrication equipment markets; and communicating the vision, strategy, and success to stakeholders. Previously, as general manager of the Etch and Selective Products business unit, he led development and commercialization of the Sym3 Etch system that grew etch revenue from less than \$400M to over \$2B and gained more than 15 pts of conductor etch market share. Earlier, as general manager of the RTP group, he led development of the Vantage Radiance system, the basis of Applied's leadership in thermal processing. He received his undergraduate degree in metallurgical engineering from the Indian Institute of Technology, Chennai, and his Ph.D. in materials science and engineering from the University of Minnesota.

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**MICHAEL SULLIVAN**  
**Corporate Vice President**  
Investor Relations

Michael Sullivan is Corporate Vice President and head of Investor Relations. His team is responsible for investor relations and marketing communications including media relations, product and technology communications, and industry events. Mr. Sullivan joined Applied in 2009 after working at Intel Corporation for 16 years. He was Intel's primary interface to equity analysts and the company's largest institutional shareholders in the U.S. and Europe. He also held corporate communications positions at the company's U.S. and European offices, where he drove corporate and competitive initiatives, new microprocessor introductions, computing platform campaigns, and flash memory PR. Mr. Sullivan is past president of the Silicon Valley chapter of NIRI, the National Investor Relations Institute. He earned his MBA at Santa Clara University and his BA in Public Relations at San Jose State University.